

ABSTRACT OF THE DISCLOSURE

A liquid thermal management socket system for thermally managing an electronic device in a socket. The liquid thermal management socket system includes a thermal management unit having a chamber for receiving one or more electronic devices, a plurality of first connectors within the thermal management unit for electrically coupling with the electronic device, and a plurality of second connectors electrically coupled to the first connectors, wherein the second connectors extend from the thermal management unit for electrically coupling within a socket unit on a board. The thermal management unit may have a cap member attachable to a base portion in a sealed manner. The chamber within the thermal management unit may thermally manage an electronic device within via spray cooling, liquid immersion or other liquid cooling method.